

# SOT1652-1

FBGA780, plastic, fine-pitch ball grid array; 780 bumps; 0.8 mm pitch; 23 mm x 23 mm x 1.92 mm body

22 February 2019

Package information

## 1 Package summary

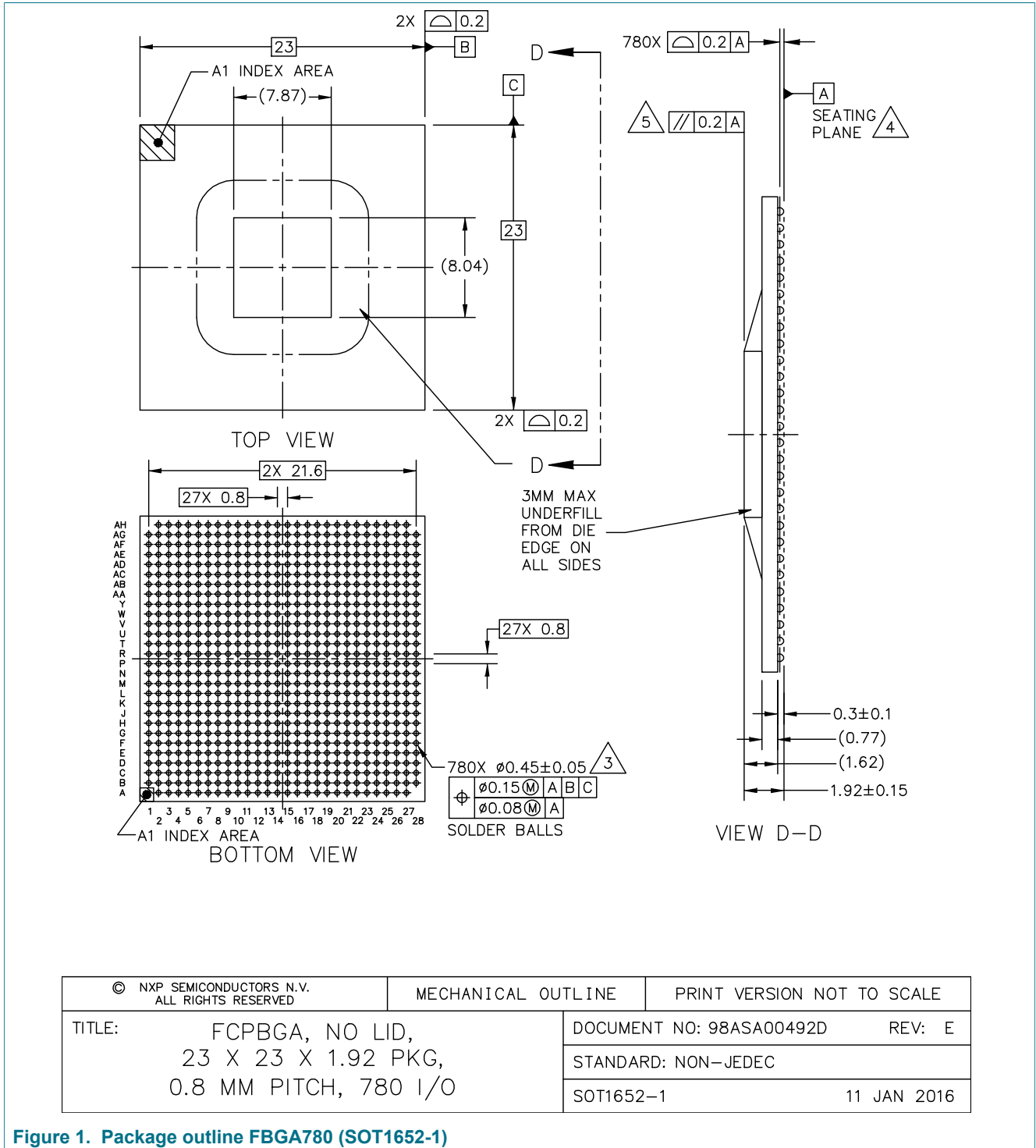
<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	FBGA780
<b>Package style descriptive code</b>	FBGA (fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	11-01-2016
<b>Manufacturer package code</b>	98ASA00492D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	23	-	mm
package width	-	23	-	mm
seated height	-	1.92	2.07	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	780	-	



2 Package outline



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TITLE: FCPBGA, NO LID, 23 X 23 X 1.92 PKG, 0.8 MM PITCH, 780 I/O	DOCUMENT NO: 98ASA00492D	REV: E
	STANDARD: NON-JEDEC	
	SOT1652-1	11 JAN 2016

Figure 1. Package outline FBGA780 (SOT1652-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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	STANDARD: NON-JEDEC		
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Figure 2. Package outline note FBGA780 (SOT1652-1)

### 3 Legal information

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